

Specification for Approval

DEVICE NUMBER: BL-HJDGKKC32M-A

SAMPLES ATTACHED AREA

PAGE DATE	1	2	3	4	5	6	7	8	9	CONTENTS
2018/6/29	1.0	1.0	1.0	1.0	1.0	1.0	1.0	1.0	1.0	Initial Released

FOR CUSTOMER'S APPROVAL STAMP OR SIGNATURE

APPROVED	PURCHASE	MANUFACTURE	QUALITY	ENGINEERING

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ISSUED	APPROVED	PREPARED
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BL-HJDGKKC32M-A

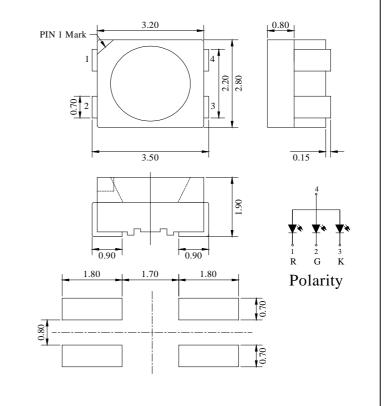
Features:

- 1. Emitted Color: Red, Green and Yellow.
- 2. Lens Appearance: Water Clear.
- 3. 3.5x2.8x1.9mm standard package.
- 4. Suitable for all SMT assembly methods.
- Compatible with infrared and vapor phase reflow solder process.
- Compatible with automatic placement equipment.
- 7. This product doesn't contain restriction Substance, comply ROHS standard.

Applications:

- 1. Automotive lighting.
- 2. Backlighting: LCDs, Key padadvertising.
- 3. Status indicators: Consumer & industrial electronics.
- 4. General use.

●Package Dimensions:



NOTES:

- 1.All dimensions are in millimeters (inches).
- 2.Tolerance is ±0.10mm (0.004") unless otherwise specified.
- 3. Specifications are subject to change without notice.

■ Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Color	Rating	Unit		
		Red	75			
Power Dissipation	P_{D}	Green	120	mW		
		Yellow	75			
Forward Current	I _F		30	mA		
Peak Forward Current*1	I _{FP}		100	mA		
Reverse Voltage	V_R		5	V		
Operating Temperature	Topr		-40℃~85℃	-		
Storage Temperature	Tstg		Tstg		-40°C ~100°C	-
Soldering Temperature		Tsol	See Page 7	-		

^{*1}Condition for I_{EP} is pulse of 1/10 duty and 3 msec width.

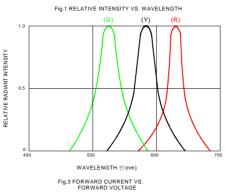


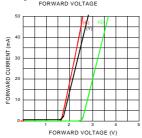
BL-HJDGKKC32M-A

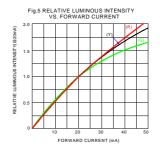
■ Electrical and optical characteristics(Ta=25°C)

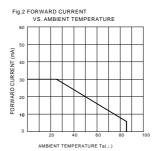
Parameter	Symbol	Condition	Color	Min.	Тур.	Max.	Unit
			Red	1.8	2.0	2.5	
Forward Voltage	V_{F}	I _F =20mA	Green	2.8	3.2	3.6	V
			Yellow	1.8	2.0	2.5	
			Red	-	220	-	
Luminous Intensity	lv	I _F =20mA	Green	-	1800	-	mcd
			Yellow	-	300]
	λр	I _F =20mA	Red	-	630	-	nm
Peak Wavelength			Green	-	525	-	
			Yellow	-	590	-	
	λd	I _F =20mA	Red	619	-	630	
Dominant Wavelength			Green	520	-	530	nm
			Yellow	586	-	594	
			Red	-	20	-	
Spectral Line Half-width	Δλ	I _F =20mA	Green	-	30	-	nm
			Yellow	-	30	-	
Reverse Current	I_R	V _R =5V		-	-	10	μA
Viewing Angle	$2\theta_{1/2}$	I _F =20mA		-	120	-	degree

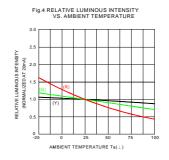
■ Typical Electro-Optical Characteristics Curves

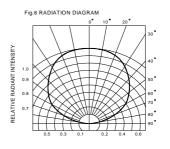








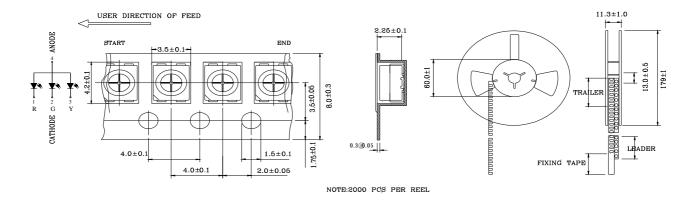




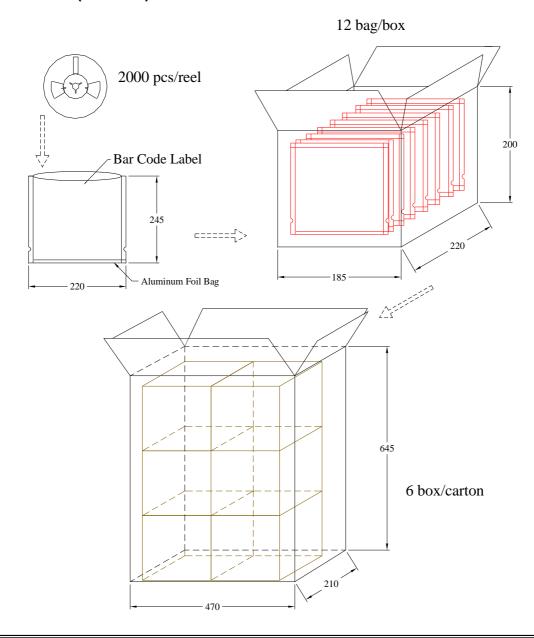


BL-HJDGKKC32M-A

Tapping and packaging specifications(Units: mm)



● Package Method:(unit:mm)





BL-HJDGKKC32M-A

● Bin Limits (At 20mA)

Intensity Bin Limits (At 20 mA) (JD)

COLOR	RED				
ITEM	Iv (n	ncd)	λ d (nm)		
Spec	140-	-475	619-630		
BIN	MIN MAX		MIN	MAX	
R	140	210			
S	210	317	619	630	
Т	317	475			

Intensity Bin Limits (At 20 mA) (GK)

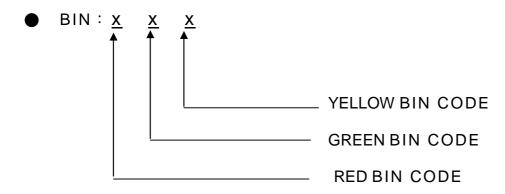
COLOR	Gre		een		
ITEM	Iv (mcd)		λ d (nm)		
Spec	715-	2400	520	-530	
BIN	MIN	MAX	MIN	MAX	
V5	715	1070	520	525	
V6	713	1070	525	530	
W5	1070	1600	520	525	
W6	1070		525	530	
X5	1600	2400	520	525	
X6	1600	2400	525	530	



BL-HJDGKKC32M-A

Intensity Bin Limits (At 20 mA) (KC)

COLOR		YEL	LOW		
ITEM	Iv (n	ncd)	λ d (nm)		
Spec	140	-475	586-594		
BIN	MIN	MAX	MIN	MAX	
R3			586	588	
R4	140	210	588	590	
R5			590	592	
R6			592	594	
S3		317	586	588	
S4	240		588	590	
S5	210		590	592	
S6			592	594	
Т3			586	588	
T4	317	175	588	590	
T5		475	590	592	
T6			592	594	



Notes:

- 1. Iv: Tolerance for each Bin limit is ± 15 %
- 2. λd: Tolerance for each Bin limit is ± 1nm
- 3. Bin categories are established for classification of products. Products may not be available in all bin categories.



BL-HJDGKKC32M-A

Reliability Test

Classification	Test Item	Reference Standard	Test Conditions	Result
	Operation Life	MIL-STD-750:1026 MIL-STD-883:1005 JIS-C-7021 :B-1	I _F =20mA Ta=Under room temperature Test time=1,000hrs	0/20
Endurance	High Temperature High Humidity Storage	MIL-STD-202:103B JIS-C-7021 :B-11	Ta=+65°C±5°C RH=90%-95% Test time=240hrs	0/20
Test	High Temperature Storage	MIL-STD-883:1008 JIS-C-7021 :B-10	High Ta=+85°C±5°C Test time=1,000hrs	0/20
	Low Temperature Storage	JIS-C-7021 :B-12	Low Ta=-35°C±5°C Test time=1,000hrs	0/20
	Temperature Cycling	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1010 JIS-C-7021 :A-4	-35°C ~ $+25$ °C ~ $+85$ °C ~ $+25$ °C 60min 20min 60min 20min Test Time=5cycle	0/20
Environmental Test	Thermal Shock	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1011	-35°C±5°C ~+85°C±5°C 20min 20min Test Time=10cycle	0/20
	Solder Resistance	MIL-STD-202:201A MIL-STD-750:2031 JIS-C-7021 :A-1	Preheating: 140°C-160°C, within 2 minutes. Operation heating: 260°C (Max.), within 10seconds. (Max.)	0/20

Judgment criteria of failure for the reliability

Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Forward voltage	V _F (V)	I _F =20mA	Over U ¹ x1.2
Reverse current	I _R (uA)	V _R =5V	Over U ¹ x2
Luminous intensity	lv (mcd)	I _F =20mA	Below S ¹ X0.5

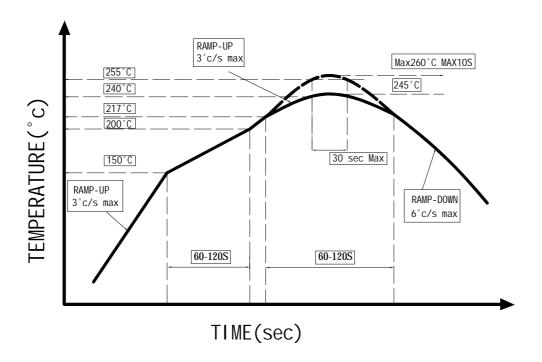
Note: 1. U means the upper limit of specified characteristics. S means initial value.

2. After each test, remove test pieces, wait for 2 hours and test pieces have returned to ambient temperature, then take next measurement.

Ver.1.0 Page: 6 of 9

BL-HJDGKKC32M-A

●IR-Reflow



- 1. Avoid any external stress applied to the resin while the LEDs are at high temperature, especially during soldering.
- 2. Avoid rapid cooling or any excess vibration during temperature ramp-down process
- Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs
- ●IRON Soldering 350°C Within 3 sec, one time only.



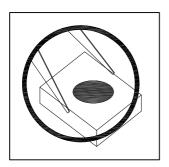
BL-HJDGKKC32M-A

Handling Precautions

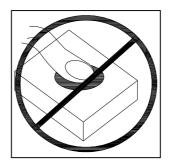
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

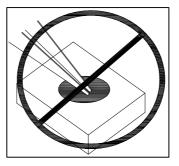
- 1. Handle the component along the side surfaces by using forceps or appropriate tools.(pic.1)
- 2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry. (pic.2,pic.3)
- 3. Do not stack together assembled PCBs, containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry. (pic.4)
- 4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible. (pic.5)
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup. (pic.5)
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production. (pic.5)



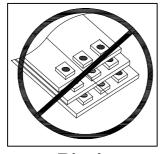
Pic.1



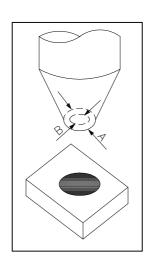
Pic.2



Pic.3



Pic.4



Pic.5



BL-HJDGKKC32M-A

Notes for designing:

Care must be taken to provide the current limiting resistor in the circuit so as to drive the LEDs within the rated figures. Also, caution should be taken not to overload LEDs with instantaneous voltage at the turning ON and OFF of the circuit.

When using the pulse drive care must be taken to keep the average current within the rated figures. Also, the circuit should be designed so as be subjected to reverse voltage when turning off the LEDs.

Storage:

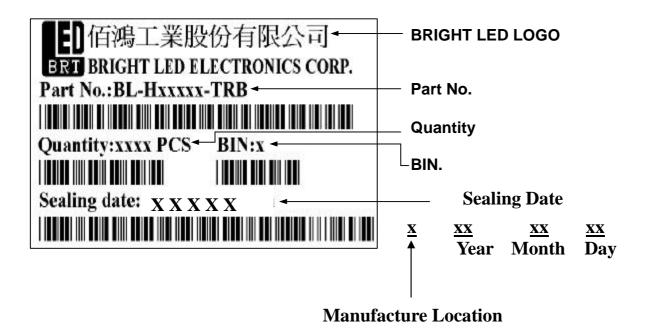
In order to avoid the absorption of moisture, it is recommended to solder LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

- (1) Temperature: 5°C-30°C(41°F)Humidity: RH 60% Max.
- (2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:
- a. Completed within 168 hours.
- b. Stored at less than 30% RH.
- (3) Devices require baking before mounting, if: 2a or 2b is not met.
- (4) If baking is required, devices must be baked under below conditions: 48 hours at 60°C±3°C.

Package and Label of Products:

- (1) Package: Products are packed in one bag of 2000 pcs (one taping reel) and a label is attached to each bag.
- (2) Label:



Ver.1.0 Page: 9 of 9